**ON Semiconductor** 

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# Onsemi

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100 V, 5.1 mΩ, 105 A

# NTMFS005N10MCL

#### Features

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free, Beryllium Free and are RoHS Compliant

#### **Typical Applications**

- Synchronous Rectification
- AC-DC and DC-DC Power Supplies
- AC-DC Adapters (USB PD) SR
- Load Switch

#### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V <sub>DSS</sub>	100	V	
Gate-to-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current $R_{\theta JC}$ (Note 1)	Steady	T <sub>C</sub> = 25°C	Ι <sub>D</sub>	105	A
Power Dissipation $R_{\theta JC}$ (Note 1)	State		PD	125	W
Continuous Drain Current R <sub>θJA</sub> (Notes 1, 2)	Steady State	$T_A = 25^{\circ}C$	۱ <sub>D</sub>	16	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)	Sidle		PD	3	W
Pulsed Drain Current	$T_A = 25^{\circ}C$ , $t_p = 100 \ \mu s$		I <sub>DM</sub>	470	А
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub> –55 t +175		°C	
Source Current (Body Diode)		I <sub>S</sub> 104		А	
Single Pulse Drain-to-Source Avalanche Energy (L = 1 mH, $I_{L(pk)}$ = 18.8 A)		E <sub>AS</sub>	E <sub>AS</sub> 177		
Lead Temperature Soldering Reflow for Solder- ing Purposes (1/8" from case for 10 s)		T <sub>L</sub> 260		°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 1)	$R_{\theta JC}$	1.2	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	50	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

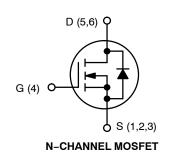
2. Surface-mounted on FR4 board using 1 in<sup>2</sup> pad size, 1 oz. Cu pad.

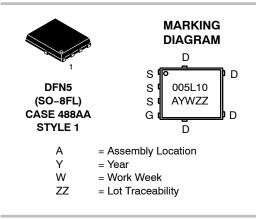


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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
100 V	5.1 mΩ @ 10 V	105 A
100 V	7.1 mΩ @ 4.5 V	105 A





#### ORDERING INFORMATION

Device	Package	Shipping†		
NTMFS005N10MCLT1G	DFN5 (Pb-Free)	1500 / Tape & Reel		

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

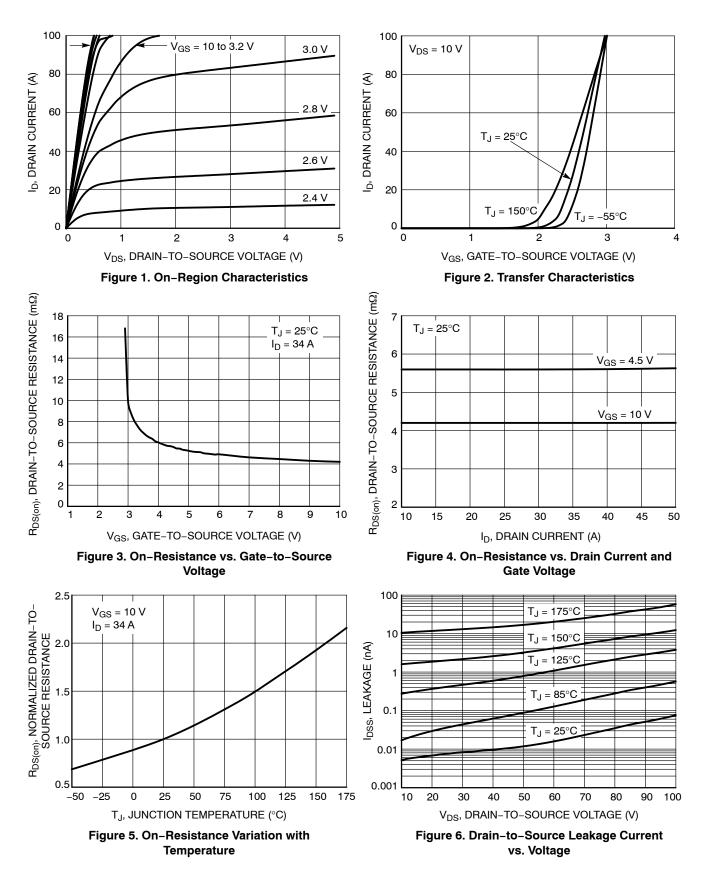
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#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise specified)

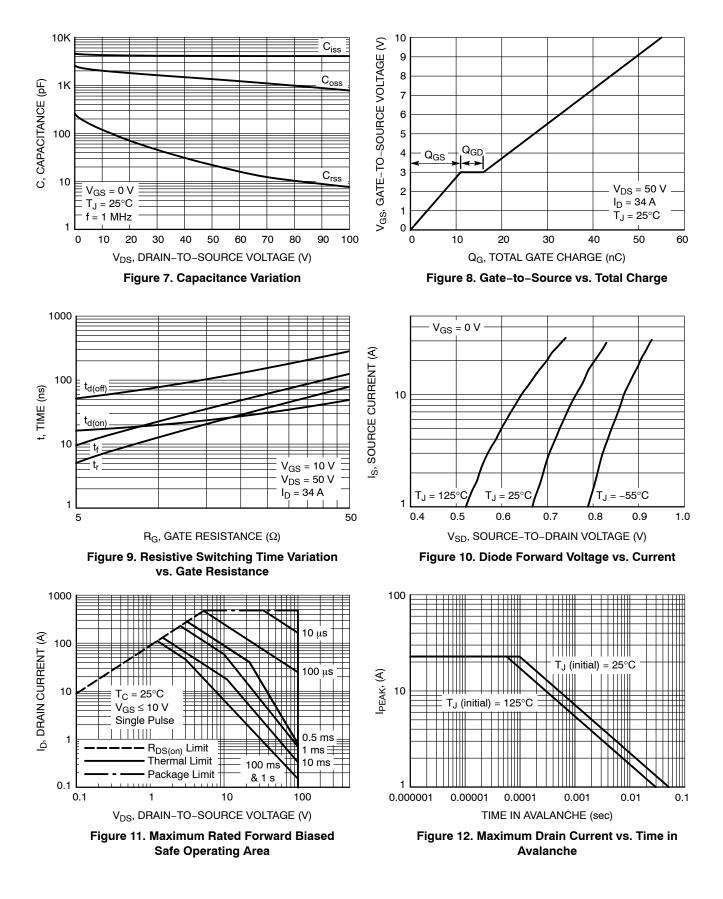
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS				-	-	-	-
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		100			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>	$I_D = 250 \ \mu\text{A}, \text{ ref to } 25^{\circ}\text{C}$			52		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V	T <sub>J</sub> = 25°C			1	μΑ
			T <sub>J</sub> = 125°C			100	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS}$	<sub>S</sub> = 20 V			100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS}$ = $V_{DS}$ , $I_D$ = 192 $\mu$ A		1		3	V
Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	$I_D = 250 \ \mu\text{A}$ , ref to $25^{\circ}\text{C}$			-5.6		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 34 A			4.2	5.1	mΩ
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 27 A			5.6	7.1	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 10 V, I <sub>E</sub>	<sub>0</sub> = 50 A		155		S
Gate-Resistance	R <sub>G</sub>	T <sub>A</sub> = 25°C			0.85		Ω
CHARGES & CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 50 V			4100		pF
Output Capacitance	C <sub>OSS</sub>				1350		
Reverse Transfer Capacitance	C <sub>RSS</sub>				22		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 4.5 V, $V_{DS}$ = 50 V, $I_{D}$ = 34 A			26		nC
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 50 V, $I_{D}$ = 34 A			55		nC
Gate-to-Source Charge	Q <sub>GS</sub>				11		
Gate-to-Drain Charge	Q <sub>GD</sub>				5		
Plateau Voltage	V <sub>GP</sub>				3		V
Output Charge	Q <sub>OSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 50 V			87		nC
SWITCHING CHARACTERISTICS (Note	3)						
Turn–On Delay Time	t <sub>d(ON)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 50 V, $I_{D}$ = 34 A, $R_{G}$ = 6 $\Omega$			17		ns
Rise Time	t <sub>r</sub>				6.7		
Turn-Off Delay Time	t <sub>d(OFF)</sub>				57		
Fall Time	t <sub>f</sub>				12.3		
DRAIN-SOURCE DIODE CHARACTERI					I	1	
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 34 A	T <sub>J</sub> = 25°C		0.85	1.3	V
	- 50		T <sub>J</sub> = 125°C		0.73		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 V, dI_S/dt = 100 A/\mu s,$ $I_S = 17 A$			56		ns
Reverse Recovery Charge	Q <sub>RR</sub>				50		nC
Charge Time					25		
•	t <sub>a</sub>						ns
Discharge Time	t <sub>b</sub>				31		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.3. Switching characteristics are independent of operating junction temperatures

#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**



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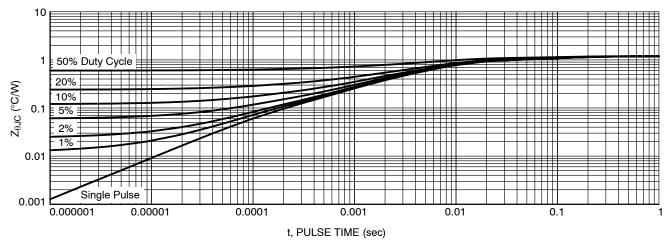
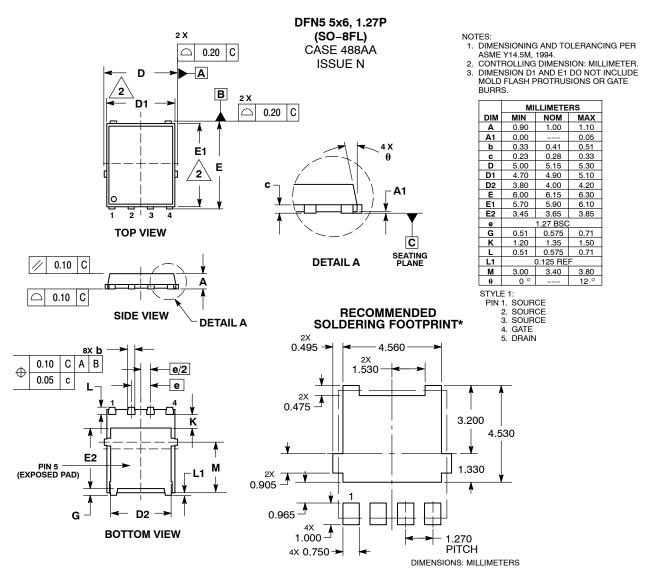


Figure 13. Thermal Response

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ON Semiconductor Website: www.onsemi.com

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